

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2397	257/678.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/15 18:00
L2	8792	semiconductor and chip and (bond\$3 adj pad) and resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/15 17:58
L3	782	L2 and (resin with (peripher\$4 or ridge))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/15 17:58
L4	593	L3 and (resin with wir\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/15 17:58
L5	341	L4 and resin.ab.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/15 17:58
L6	1522	257/692.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/15 18:01
L7	1	((semiconductor with device) and chip and circuit and (electrical adj interconnections) and (bonding adj pads) and (surface with chip) and (wirings with resin) and (ridged adj edge) and (external adj connection adj terminal)).clm.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/15 18:02
S1	8284	semiconductor and chip and (bond\$3 adj pad) and resin	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/13 17:32
S2	740	S1 and (resin with (peripher\$4 or ridge))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/13 17:33
S3	561	S2 and (resin with wir\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/13 17:33

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S4	326	S3 and resin.ab.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/15 17:58
S5	112	S4 and (resin with (peripher\$4 or ridge)).ab.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/13 17:48
S6	2	("6323542").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/13 17:48
S7	7	("5126820"   "5148266"   "5563102"   "5641113"   "5656863"   "5753974"   "5834844").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/13 17:51
S8	0	S2 and (wir\$3 with on with resin)	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/13 17:51
S9	531	S2 and (wir\$3 with resin)	US-PGPUB; USPAT; USOCR	OR	ON	2006/05/13 17:57
S10	2250	257/678.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/15 17:58